APPLICA	BLE STANI	DAKD			ICTOP 4 C							
OPERATING TEMPERATURI		E RANGE							TO 50 °C (PACKED CONDIT			
RATING	VOLTAGE		50 V	AC / DC	HUMIDITY F		JANUE	RE	LATIVE	HUMIDITY 90 % MAX (NOT DEV	VED)	
	CURRENT		ſ	).5 A	APPLICA	BLE CABLE		t=0.3±	:0.05n	nm, GOLD PLATING.(4~3	0 PO	S.)
	JOHNEINI		0.5 A		012:0	A = : 0 :		$t=0.3\pm0.$	.03mm	, GOLD PLATING.(OVEF	R 31 P	OS.
		Т				OITA	<u>VS</u>				1	1
	EM		7	EST METHOD	)			F	REQU	REMENTS	QT	Α
CONSTR		MELIALI	V AND DV	MEASURING	INICTOLIN	/ENIT	IACCC	DRDING 1	TO DB	AWING	1	1
MARKING	AAMINATION		MED VISU		INSTRUM	/ICINI.	ACCC	ושחושחל	וט טה	AWING.	×	×
	CAL CHAP										^	1_^
VOLTAGE P		RACTERISTICS 150 V AC FOR 1 min.					NO FL	ASHOVE	ER OF	R BREAKDOWN.	×	T ×
INSULATION		100 V DC.					500 M	MIN.			×	×
RESISTANC		AC 20 m	/ MAY / 1	KHz), 1 mA			50 mc	O. MAX.				
CONTACTA	LOIOTANUE	AO ZU III	v iviAV ( I i	INIZ), IIIIA	•		00		)( EF	C BULK RESISTANCE	×	×
							(L=8mr		-U,FF	O DULK RESISTANCE		
MECHAN	IICAL CHA	RACTE	RISTIC	S			,	•			1	1
SHOCK S		FREQUENCY 10 TO 55 Hz, HALF AMPLITUDE					① NO ELECTRICAL DISCONTINUITY OF			×	_	
		0.75 mm, — m/s <sup>2</sup> FOR 10 CYCLES IN 3 AXIAL DIRECTIONS.				1 μs. ② CONTACT RESISTANCE: $50 \text{ m}\Omega$ MAX.						
		981 m/s <sup>2</sup> , DURATION OF PULSE 6 ms				③ NO DAMAGE, CRACK AND LOOSENESS			×	-		
				3 BOTH AXIA				OF PARTS.  ① CONTACT RESISTANCE: 50 mΩ MAX.				
OPERATION		20 HIVIES	20 TIMES INSERTIONS AND EXTRACTIONS.			② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.			×			
(TH		(THICKN	MEASURED BY APPLICABLE FPC. [THICKNESS OF FPC SHALL BE t=0.30mm AT INITIAL CONDITION.)			DIRECTION OF INSERTION: 0.3N×n MIN.(4~30 POS.)			×	-		
	MENTAL						0.21	N×n MIN	I.(OVE	R 31 POS.) (note 1)		
_		_	_	2 ℃ , 5 % SA	LT WATE	R	① CC	ONTACT	RESIS	STANCE: 100 mΩ MAX.	×	
		SPRAY FOR 96 h.				2 NC	DAMAG	GE, CR	ACK AND LOOSENESS			
						OF PARTS.  ③ NO EVIDENCE OF CORROSION WHICH						
						AFFECTS TO OPERATION OF						
BADID CHAI	NGE OF					CONNECTOR.						
RAPID CHANGE OF TEMPERATURE		TEMPERATURE-55 $\rightarrow$ +15TO+35 $\rightarrow$ +85 $\rightarrow$ +15TO+35 $^{\circ}$ C TIME 30 $\rightarrow$ 2TO 3 $\rightarrow$ 30 $\rightarrow$ 2TO 3				② INSULATION RESISTANCE: $50 \text{ M}\Omega$ MIN.				×		
		min				③ NO DAMAGE, CRACK AND LOOSENESS						
DAMP HEAT	-	UNDER 5 CYCLES.  EXPOSED AT 40±2 °C,				OF	PARTS.			×	-	
(STEADY ST	TATE)	RELATIV	/E HUMIDI	TY 90 TO 9		96 h.					_^	
DAMP HEAT,CYCLIC		EXPOSED AT -10 TO +65 °C, RELATIVE HUMIDITY 90 TO 96 %, 10 CYCLES,TOTAL 240 h.				① CONTACT RESISTANCE: 50 mΩ MAX. > 2 INSULATION RESISTANCE: 1 MΩ MIN.				×	_	
							(AT HIGH HUMIDITY)					
							3 INS	$\center{3}$ INSULATION RESISTANCE: 50 M $\Omega$ MIN.				
						(AT DRY)  ① NO DAMAGE, CRACK AND LOOSENESS OF PARTS.						
COUN	T DE	SCRIPTION	ON OF RE	VISIONS		DESIG				CHECKED	DATE	
<b>Q</b>									<u> </u>			
REMARK							APPROVED		OVED	NF. MIYAZAKI	16.0	)8. 3 <sup>-</sup>
							CHECKED		KED	YH. MICHIDA	16.0	)8. 3 <sup>-</sup>
			(IEQ 00540				DESIGNED KN. KOBAYASHI			KN. KOBAYASHI	16. 08. 31	
Unless otherwise specified, refer to IEC 60512.				DRAV	WN	RK. OGASAWARA	16.0	)8. 3				
Note QT:Qualification Test AT:Assurance Test X:Applicable Test				DF	RAWING NO. ELC-156169-9			9-00	)			
SPECIFICATION SH					!		NO. F		FH	l33−**S−0. 5SH (99)		1
HIROSE E			LECTRIC CO., LTD. CODE			CODE	E NO. CL580			⚠	1/2	

SPECIFICATIONS								
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ				
DRY HEAT	EXPOSED AT 85±2 °C, 96 h.	① CONTACT RESISTANCE: 50 mΩ MAX.	×	_				
COLD	EXPOSED AT -55±3°C, 96 h.	② NO DAMAGE, CRACK AND LOOSENESS OF PARTS.	×	_				
SULPHUR DIOXIDE [JIS C 60068-2-42]	EXPOSED AT 40±2 °C , RELATIVE HUMIDITY 80±5% 25±5 ppm FOR 96 h.	<ol> <li>CONTACT RESISTANCE: 100 mΩ MAX.</li> <li>NO DAMAGE, CRACK AND LOOSENESS OF PARTS.</li> </ol>	×	_				
HYDROGEN SULPHIDE [JIS C 60068-2-43]	EXPOSED AT $40\pm2$ °C , RELATIVE HUMIDITY 80 $\pm5\%$ , 10 TO 15 ppm FOR 96 h.	③ NO EVIDENCE OF CORROSION WHICH AFFECTS TO OPERATION OF CONNECTOR.	×	_				
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 235 ±5°C FOR IMMERSION DURATION, 2±0.5 sec.	A NEW UNIFORM COATING OF SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.	×	_				
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING: PEAK TMP. 250 °C MAX. REFLOW TMP. OVER 230 °C WITHIN 60 sec. 2) SOLDERING IRONS: TMP. 350 ± 10 °C FOR 5±1 sec.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	×	_				

## (note1)

THIS PRODUCT HAS FLIP-LOCK CONSTRUCTION. FASTEN FPC ON PCB OR SOMETHING FIXED IF FORCE IN VERTICAL DIRECTION SHALL BE PREDICTED.

Note C	T:Qualification Test AT:Assurance Test X:Applicable Test	DRAWI	NG NO.	ELC-156169-99-00		
HR	SPECIFICATION SHEET	PART NO.	FH33-**S-0. 5SH (99)			
1.0	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	Δ	2/2